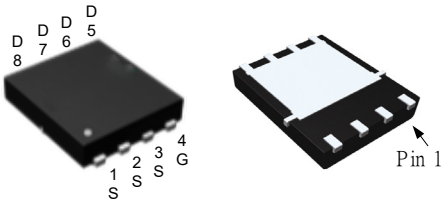
Features

- 30V/135A
  $R_{DS(ON)}$=1.8mΩ(typ.)@V_{GS}=10V
  $R_{DS(ON)}$=1.9mΩ(typ.)@V_{GS}=4.5V
- 100% UIS + R_g Tested
- Reliable and Rugged
- Lead Free and Green Devices Available (RoHS Compliant)
- Moisture Sensitivity Level MSL1 (per JEDEC J-STD-020D)

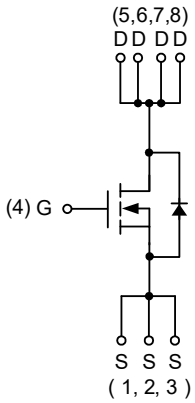
Applications

- For E-cigrate Application.
- For Auto Model Airplane.
- Synchronous Rectifier for Server.

Pin Description



DFN5x6A-8_EP



N-Channel MOSFET

Absolute Maximum Ratings (T_A=25°C Unless Otherwise Noted)

Symbol	Parameter		Rating	Unit
Common Ratings				
V_{DSS}	Drain-Source Voltage		30	V
V_{GSS}	Gate-Source Voltage		±20	
T_J	Maximum Junction Temperature		150	°C
T_{STG}	Storage Temperature Range		-55 to 150	
I_S	Diode Continuous Forward Current	T_C=25°C	135	A
I_D	Continuous Drain Current	T_C=25°C	135	A
		T_C=100°C	99	
I_{DM}[b]	Pulsed Drain Current	T_C=25°C	405	
P_D	Maximum Power Dissipation	T_C=25°C	43.1	W
		T_C=100°C	17.2	
$R_{\theta JC}$	Thermal Resistance-Junction to Case	Steady State	2.9	°C/W
$R_{\theta JA}$[c]	Thermal Resistance-Junction to Ambient	t ≤ 10s	19.5	°C/W
		Steady State	55	
I_{AS}[d]	Avalanche Current, Single pulse	L=0.1mH	69	A
E_{AS}[d]	Avalanche Energy, Single pulse	L=0.1mH	238	mJ

Note a : Calculated continuous current based on maximum allowable junction temperature. Bonding wire limitation current is 100A.
Note b : Pulse width limited by maximum junction temperature.
Note c : Surface mounted on $1in^2$ pad area, steady state t = 999s.
Note d : UIS tested and pulse width limited by maximum junction temperature (initial temperature T_j=25°C).

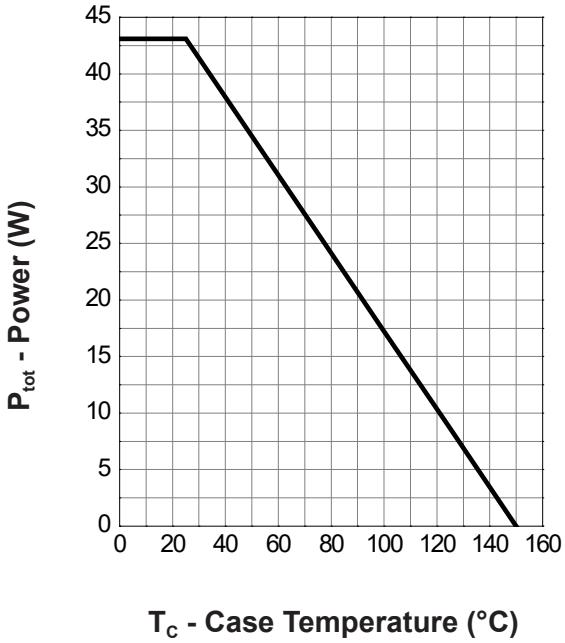
Electrical Characteristics (T_A = 25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
Static Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS}=0V, I_{DS}=250μA	30	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS}=24V, V_{GS}=0V	-	-	1	μA
		T_J=85°C	-	-	30	
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=V_{GS}, I_{DS}=250μA	1.0	1.8	2.5	V
I_{GSS}	Gate Leakage Current	V_{GS}=±20V, V_{DS}=0V	-	-	±100	nA
$R_{DS(ON)}$ [e]	Drain-Source On-state Resistance	V_{GS}=10V, I_{DS}=20A	-	1.8	2.1	mΩ
		V_{GS}=4.5V, I_{DS}=15A	-	1.9	2.5	
Gfs	Forward Transconductance	V_{DS}=5V, I_{DS}=15A	-	41	-	S
Diode Characteristics						
V_{SD} [e]	Diode Forward Voltage	I_{SD}=20A, V_{GS}=0V	-	0.77	1.1	V
t_{rr}	Reverse Recovery Time	I_{SD}=20A, dI_{SD}/dt=100A/μs	-	40.5	-	ns
t_a	Charge Time		-	20.7	-	
t_b	Discharge Time		-	19.8	-	
Q_{rr}	Reverse Recovery Charge		-	30.3	-	nC
Dynamic Characteristics [f]						
R_G	Gate Resistance	V_{GS}=0V,V_{DS}=0V,F=1MHz	-	1.1	-	Ω
C_{iss}	Input Capacitance	V_{GS}=0V, V_{DS}=15V, Frequency=1.0MHz	-	3680	4721	pF
C_{oss}	Output Capacitance		-	1215	-	
C_{rss}	Reverse Transfer Capacitance		-	125	-	
$t_{d(ON)}$	Turn-on Delay Time	V_{DD}=15V, R_L=15Ω, I_{DS}=1A, V_{GEN}=10V, R_G=6Ω	-	18	33	ns
t_r	Turn-on Rise Time		-	12	22	
$t_{d(OFF)}$	Turn-off Delay Time		-	54	98	
t_f	Turn-off Fall Time		-	70	126	
Gate Charge Characteristics [f]						
Q_g	Total Gate Charge	V_{DS}=15V, V_{GS}=10V, I_{DS}=20A	-	34.5	48	nC
Q_g	Total Gate Charge	V_{DS}=15V, V_{GS}=4.5V, I_{DS}=20A	-	17.8	-	
Q_{gth}	Threshold Gate Charge		-	3.3	-	
Q_{gs}	Gate-Source Charge		-	6	-	
Q_{gd}	Gate-Drain Charge		-	6.8	-	

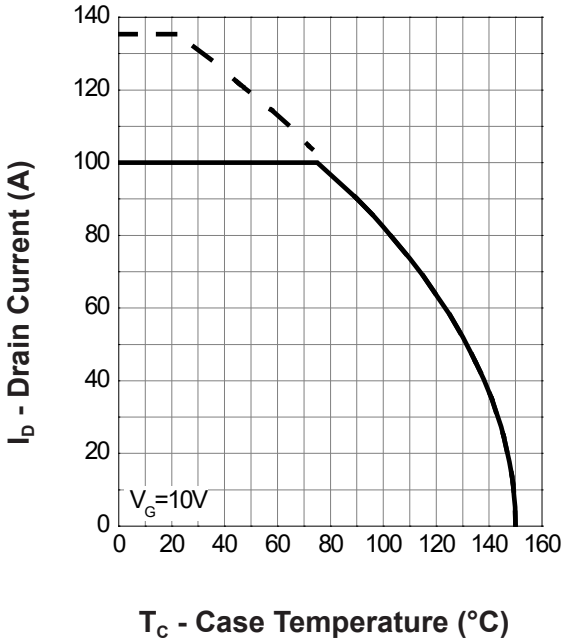
Note e：Pulse test ; pulse width≤300μs, duty cycle≤2%.
Note f：Guaranteed by design, not subject to production testing.

Typical Operating Characteristics

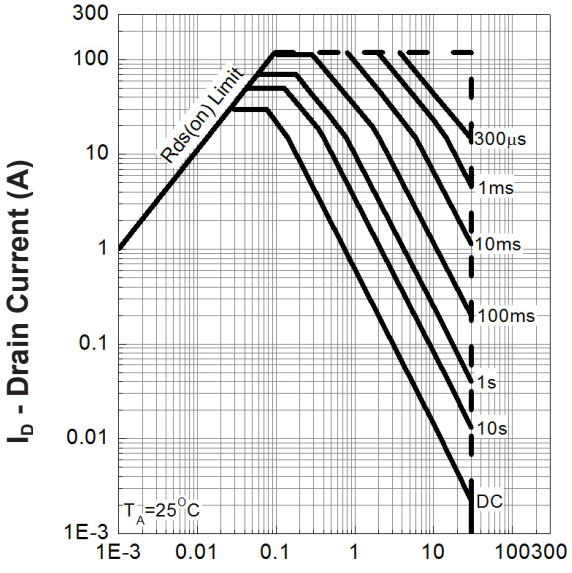
Power Dissipation



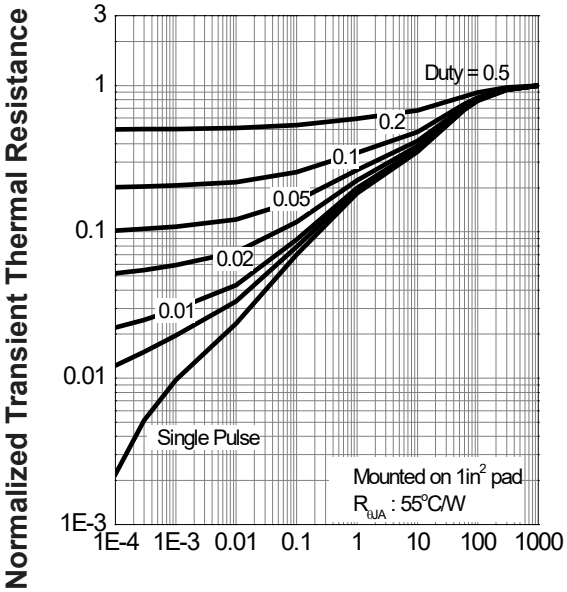
Drain Current



Safe Operation Area

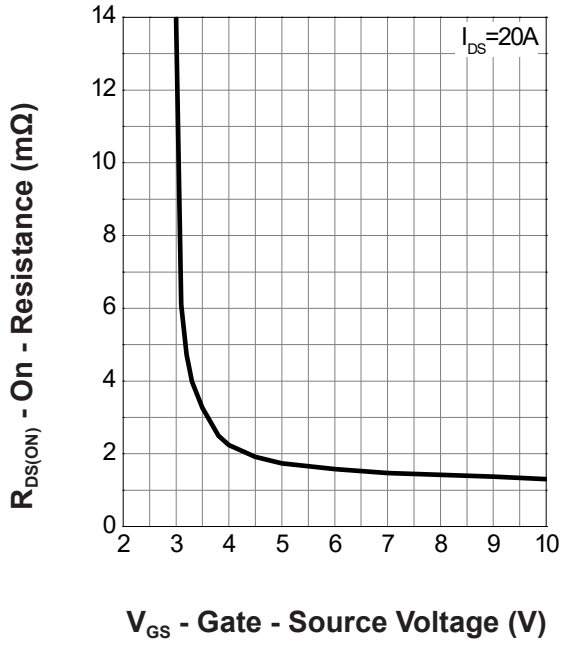


Thermal Transient Impedance

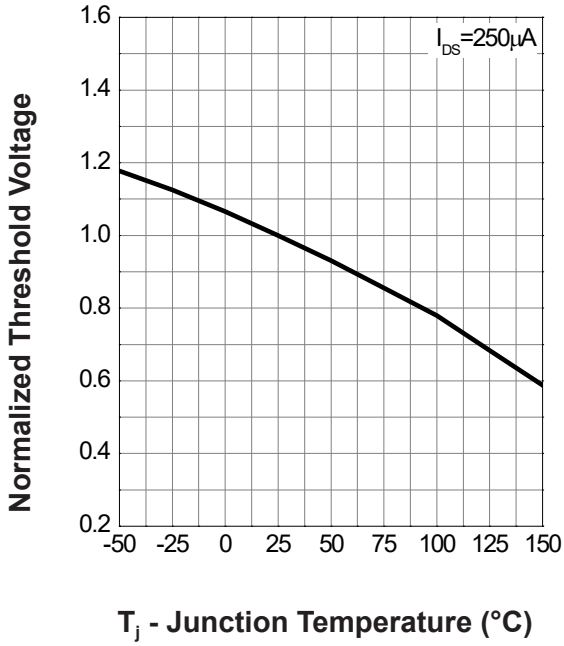


Typical Operating Characteristics(Cont.)

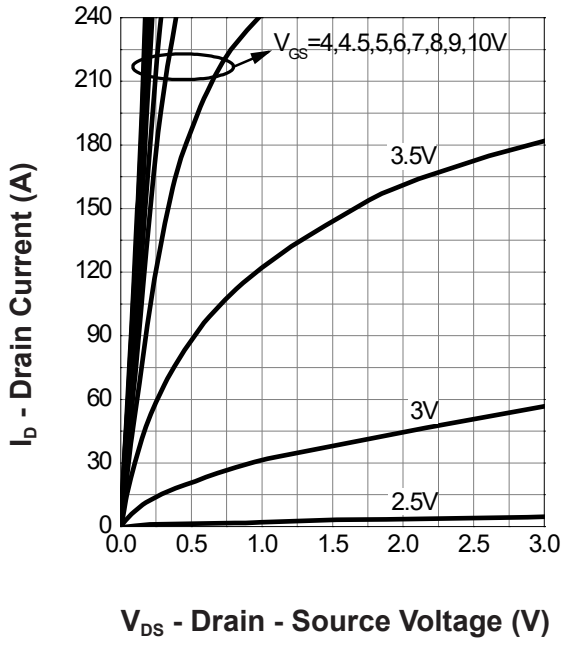
Gate-Source On Resistance



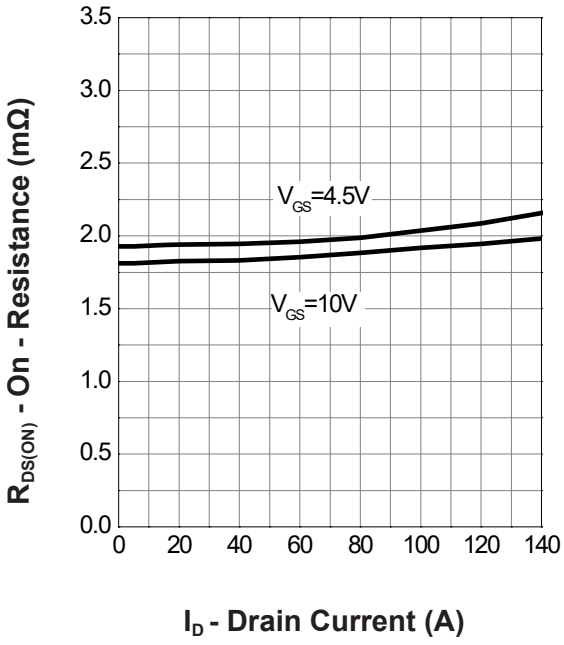
Gate Threshold Voltage



Output Characteristics

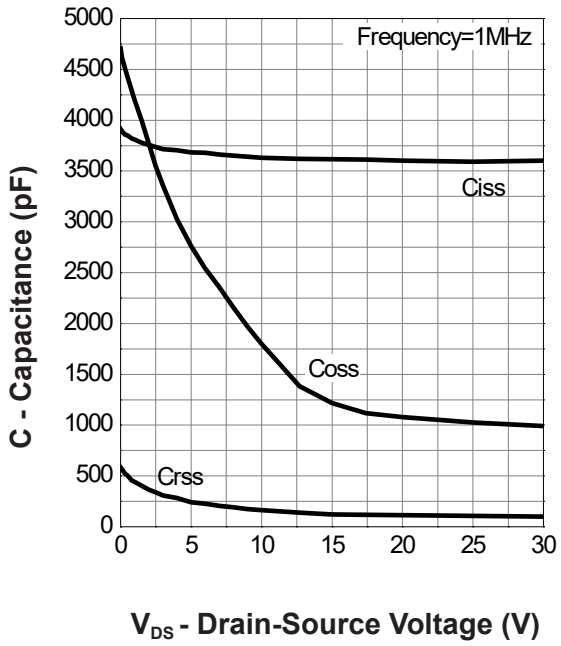


Drain-Source On Resistance

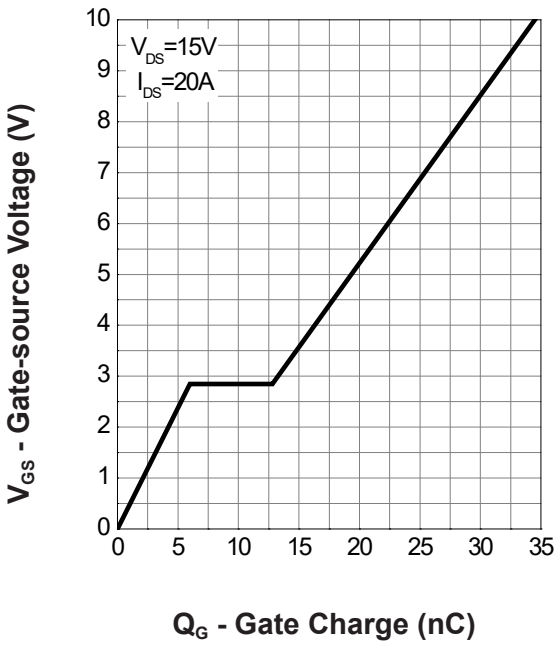


Typical Operating Characteristics(Cont.)

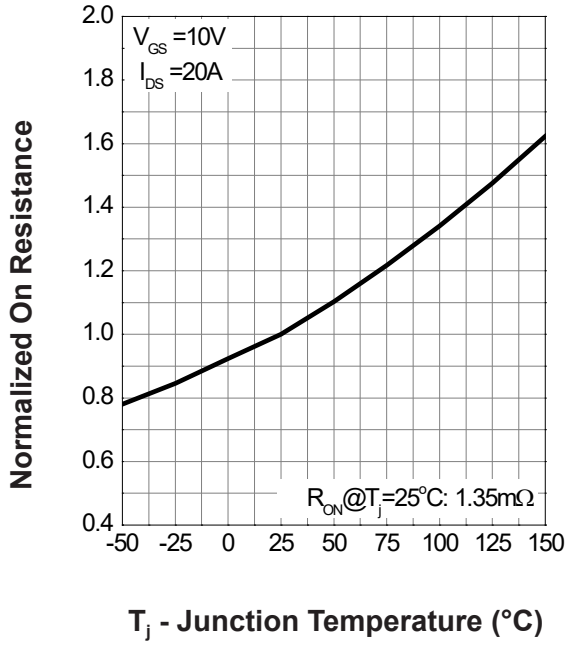
Capacitance



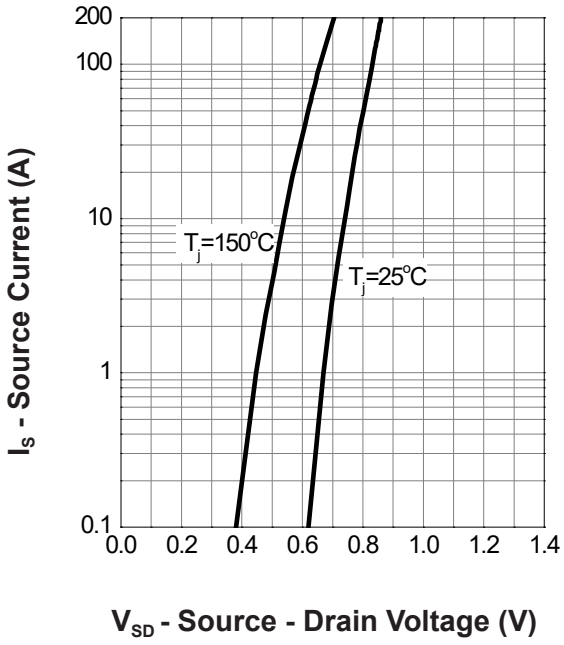
Gate Charge



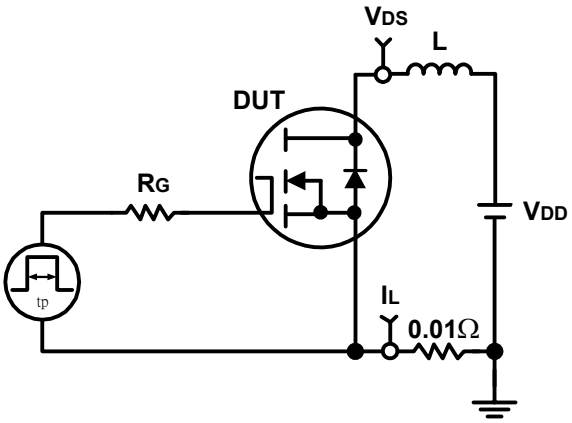
Drain-Source On Resistance

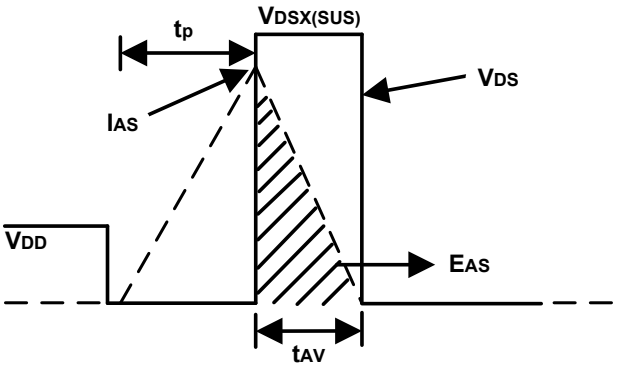


Source-Drain Diode Forward

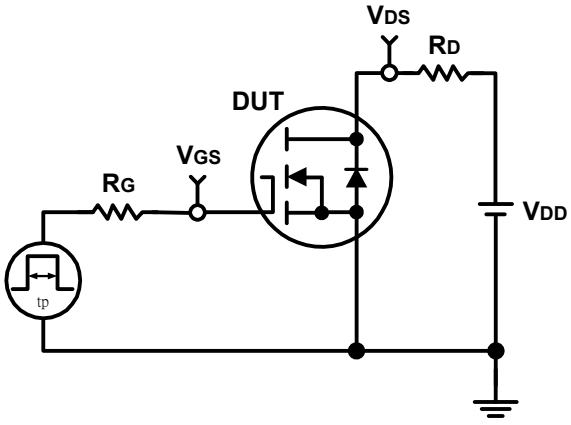


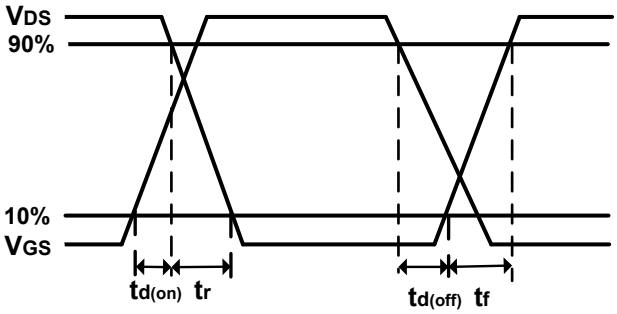
Avalanche Test Circuit and Waveforms





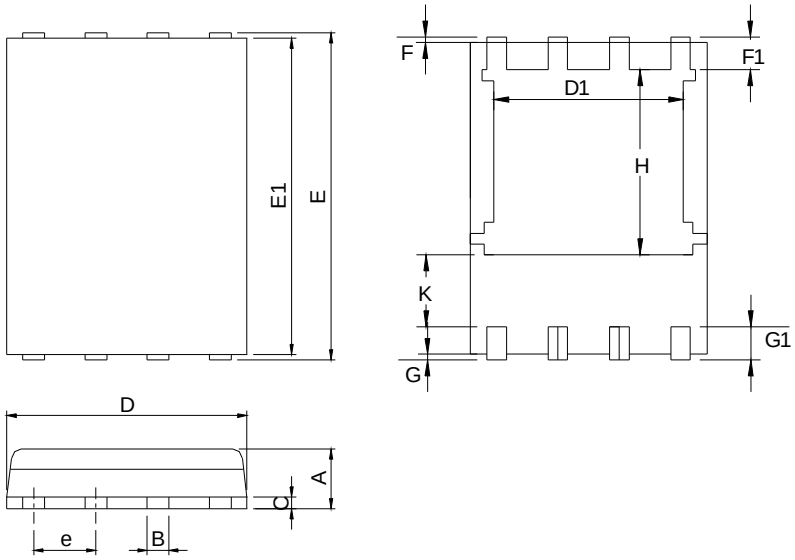
Switching Time Test Circuit and Waveforms





Package Information

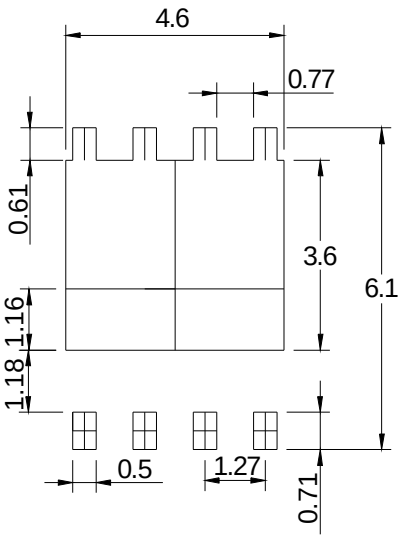
DFN5x6-8



SYMBOL	DFN5x6-8			
	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	0.90	1.20	0.035	0.047
B	0.3	0.51	0.012	0.020
C	0.19	0.25	0.007	0.010
D	4.80	5.30	0.189	0.209
D1	4.00	4.40	0.157	0.173
E	5.90	6.20	0.232	0.244
E1	5.50	5.80	0.217	0.228
e	1.27 BSC		0.050 BSC	
F	0.05	0.30	0.002	0.012
F1	0.35	0.75	0.014	0.030
G	0.05	0.30	0.002	0.012
G1	0.35	0.75	0.014	0.030
H	3.34	3.9	0.131	0.154
K	0.762	-	0.03	-

Note : 1.Dimension D, D1,D2 and E1 do not include mold flash or protrusions.
Mold flash or protrusions shall not exceed 10 mil.

RECOMMENDED LAND PATTERN



UNIT: mm